

Features

- ⊗ Frequency range : 24MHz to 66MHz
- ⊗ Ultra compact and thin
- ⊗ AuSn sealing, ceramic SMD package
- ⊗ External dimensions (mm)
L : 1.6 x W : 1.2 x H : 0.35
- ⊗ RoHS compliant & Pb free

Applications

- ⊗ BT, BLE, W-LAN, NFC
- ⊗ SiP modules
- ⊗ Mobile phone, Wearables
- ⊗ Internet of Things (IoT)
- ⊗ Portable consumer products

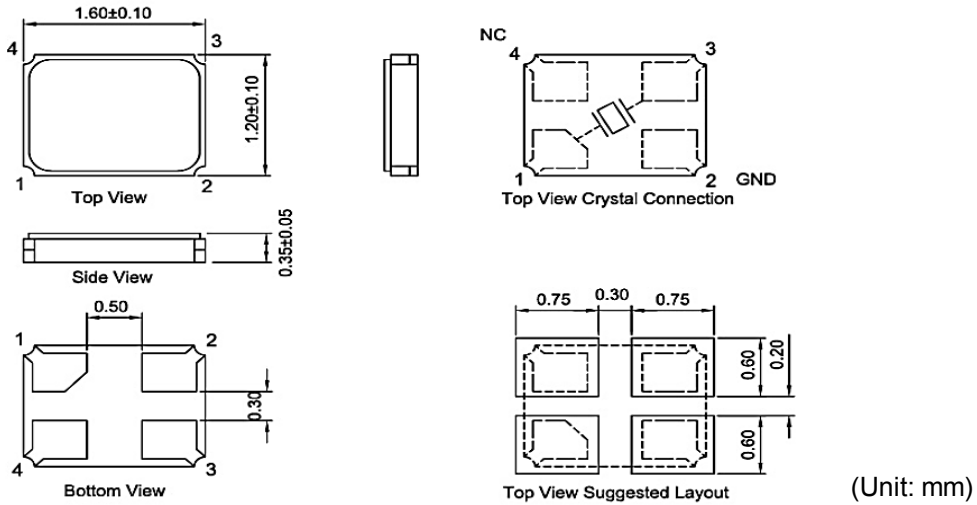
Electrical Characteristics

| Item | | 8Q | Conditions |
|--|-------------|------------------------|---------------------------|
| Frequency Range | F_0 | 24MHz ~ 66MHz | |
| Frequency Tolerance | F_{tol} | ±30ppm, ±20ppm, ±10ppm | at 25°C |
| Frequency Stability over Operating Temperature Range (refer to 25°C) | F_{stab} | ±30 ppm | -20°C ~ +70°C |
| | | ±20 ppm | |
| | | ±10 ppm | |
| | | ±10 ppm | -30°C ~ +85°C |
| | | ±30 ppm | -40°C ~ +85°C |
| | | ±20 ppm | |
| Operating Temperature Range | T_{OTR} | -20°C ~ +70°C | |
| | | -40°C ~ +85°C | |
| | | -40°C ~ +125°C | |
| Shunt Capacitance | C_0 | 3pF Max. | |
| Drive Level | D_L | 1 ~ 200μW (50μW Typ.) | |
| Load Capacitance | C_L | 6pF, 8pF, 10pF, 12pF | |
| Aging | F_{aging} | ±3 ppm Max. | at 25°C ± 3°C, first year |
| Storage Temperature Range | T_{STR} | -55°C ~ +125°C | |

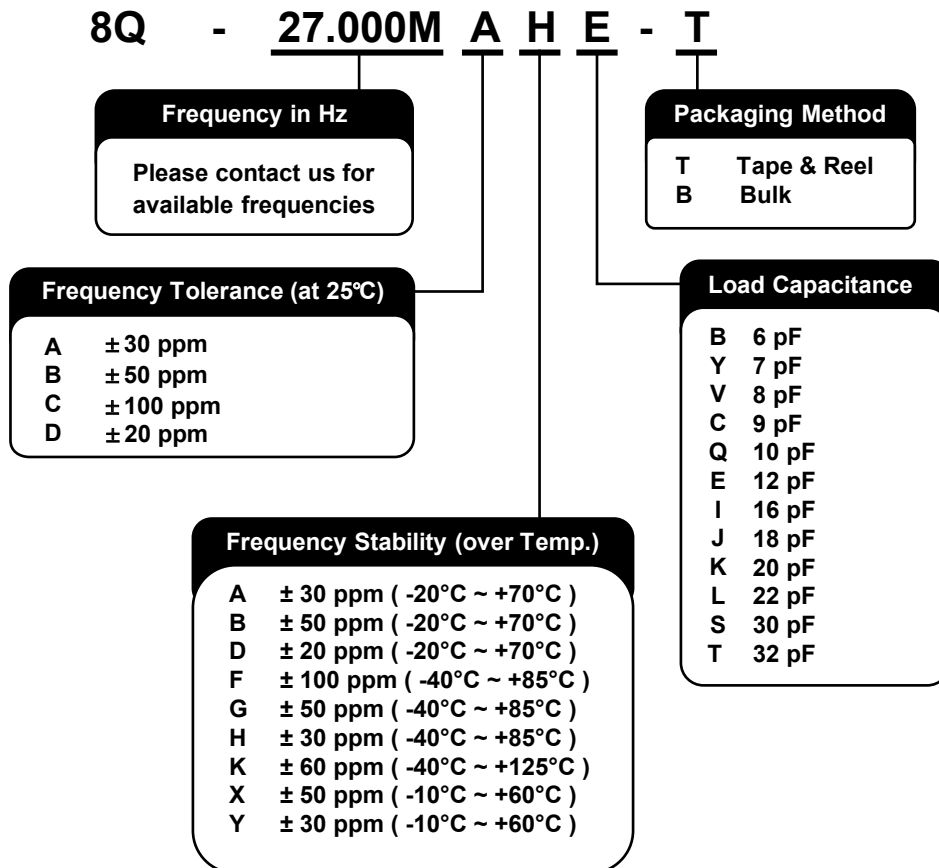
Motional Resistance (ESR)

| Fundamental | |
|-------------|-----------|
| 24 ~ 30 MHz | 100Ω Max. |
| 30 ~ 66 MHz | 80Ω Max. |

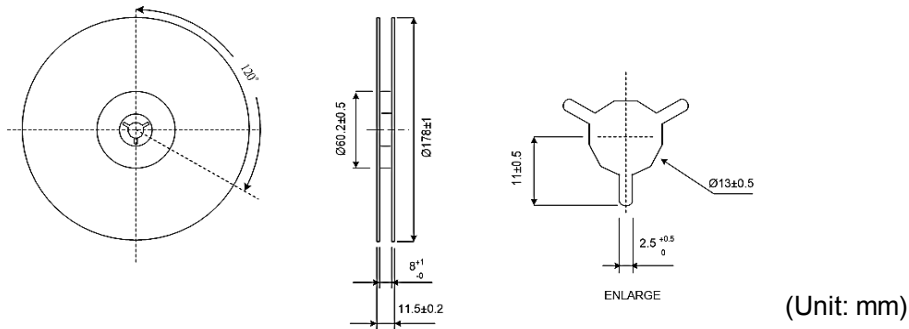
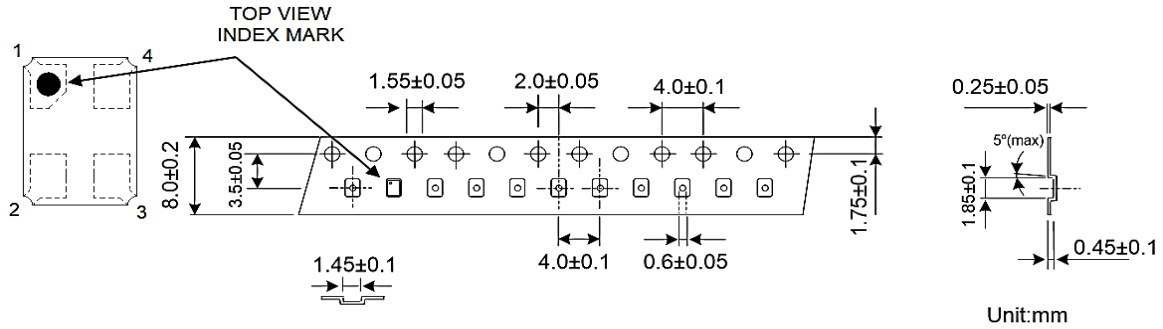
Dimensions



Ordering Information



Packing



Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

